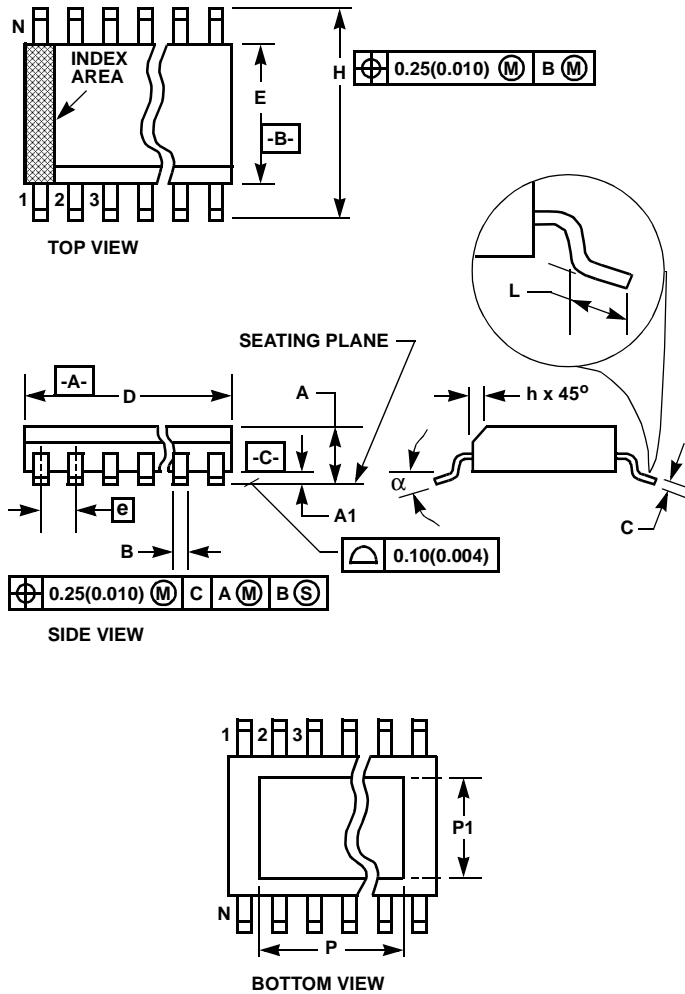


# Plastic Packages for Integrated Circuits

## Small Outline Exposed Pad Plastic Packages (EPSOIC)



### M28.3B

#### 28 LEAD WIDE BODY SMALL OUTLINE EXPOSED PAD PLASTIC PACKAGE

SYMBOL	INCHES			NOTES
	MIN	NOMINAL	MAX	
A	0.091	-	0.099	-
A1	0.001	-	0.005	-
B	0.014	-	0.019	9
C	0.0091	-	0.0125	-
D	0.701	-	0.711	3
E	0.292	-	0.299	4
e	0.050 BSC			-
H	0.400	-	0.410	-
h	0.010	-	0.016	5
L	0.024	-	0.040	6
N	28			7
$\alpha$	0°	5°	8°	-
P	0.180	0.214	0.218	11
P1	0.156	0.190	0.194	11

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#### NOTES:

- Symbols are defined in the "MO Series Symbol List" in Section 2.2 of Publication Number 95.
- Dimensioning and tolerancing per ANSI Y14.5M-1982.
- Dimension "D" does not include mold flash, protrusions or gate burrs. Mold flash, protrusion and gate burrs shall not exceed 0.15mm (0.006 inch) per side.
- Dimension "E" does not include interlead flash or protrusions. Interlead flash and protrusions shall not exceed 0.25mm (0.010 inch) per side.
- The chamfer on the body is optional. If it is not present, a visual index feature must be located within the crosshatched area.
- "L" is the length of terminal for soldering to a substrate.
- "N" is the number of terminal positions.
- Terminal numbers are shown for reference only.
- The lead width "B", as measured 0.36mm (0.014 inch) or greater above the seating plane, shall not exceed a maximum value of 0.61mm (0.024 inch)
- Controlling dimension: INCH.
- Dimensions "P" and "P1" are thermal and/or electrical enhanced variations. Values shown are maximum size of exposed pad within lead count body size.